APPLIED MATERIALS®
make possible

1. 晶片傳送/處理模組 (Wafer Handling Module)

50 years of materials innovation

晶片傳送/處理模組

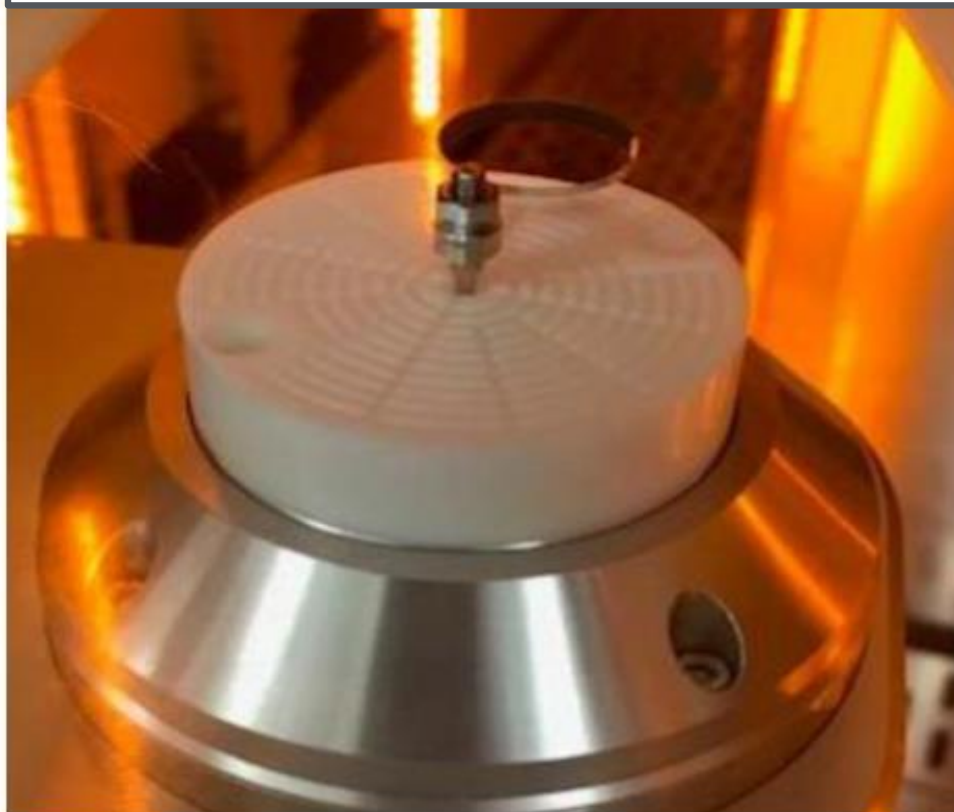
1. FI 6.3

2. E-chuck

3-1. Open Cassette

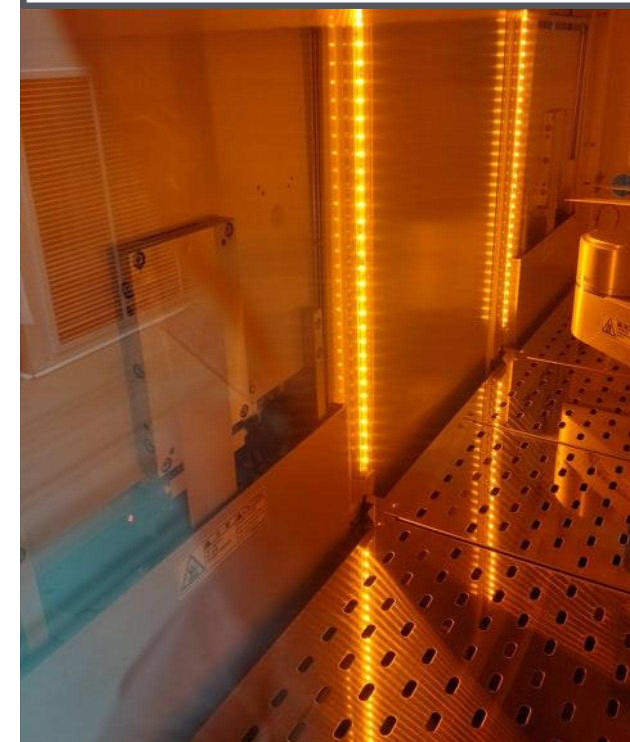
晶片傳送/處理模組

3-2. Aligner



3-3. Cassette sensor

3-4. Complete Wafer Mapping System



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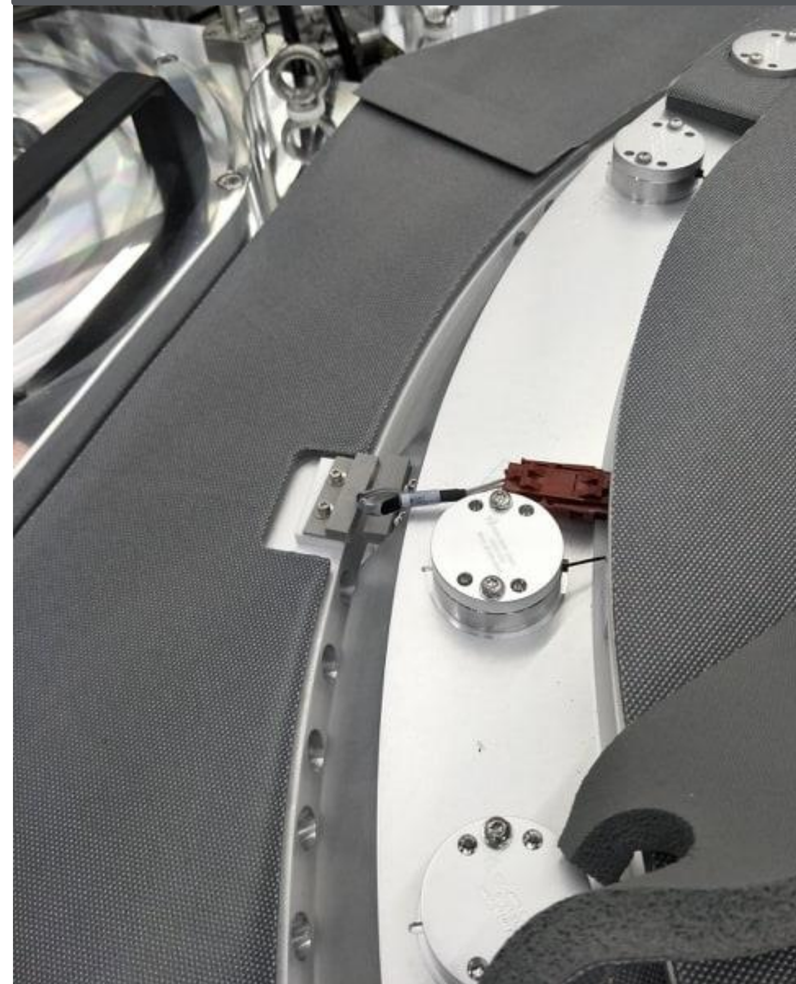
晶片傳送/處理模組

4. Ceramic Blade (FABS)

5. Robot door interlock system



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2. 製程區

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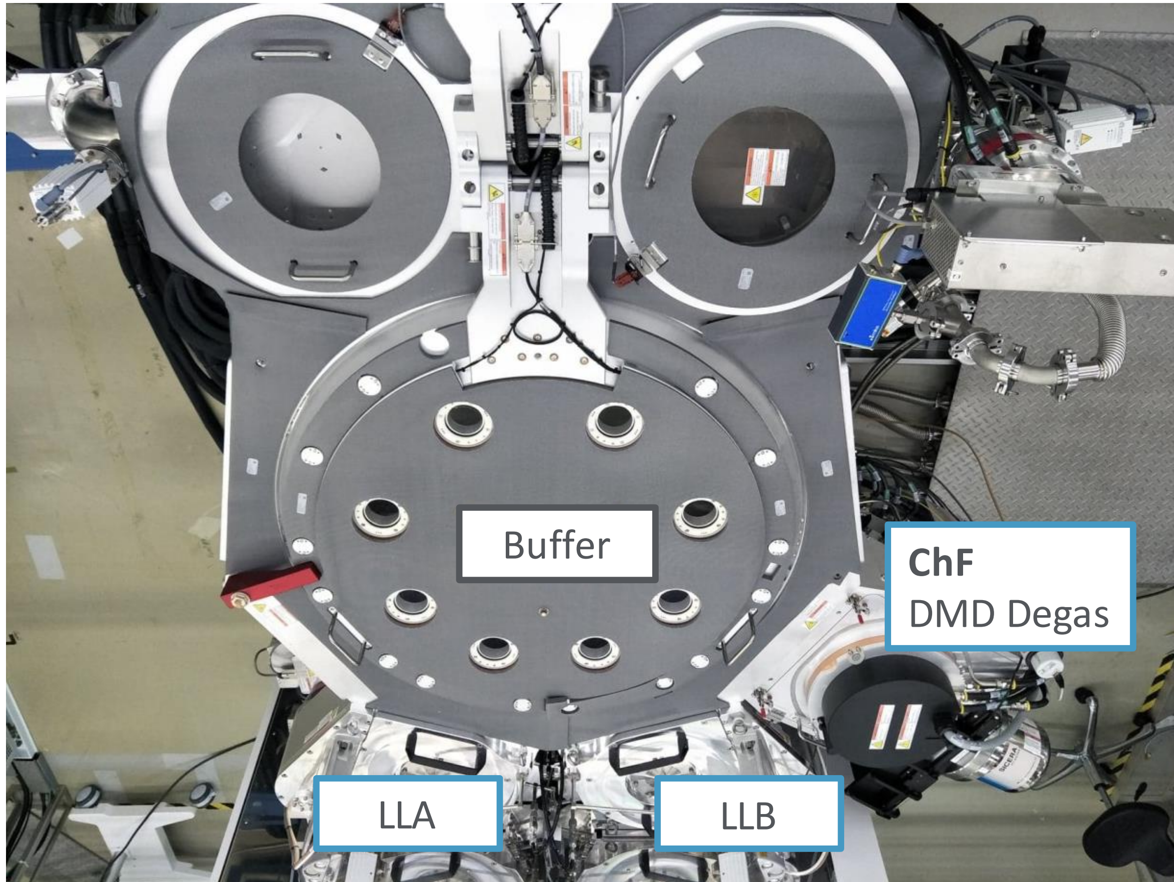
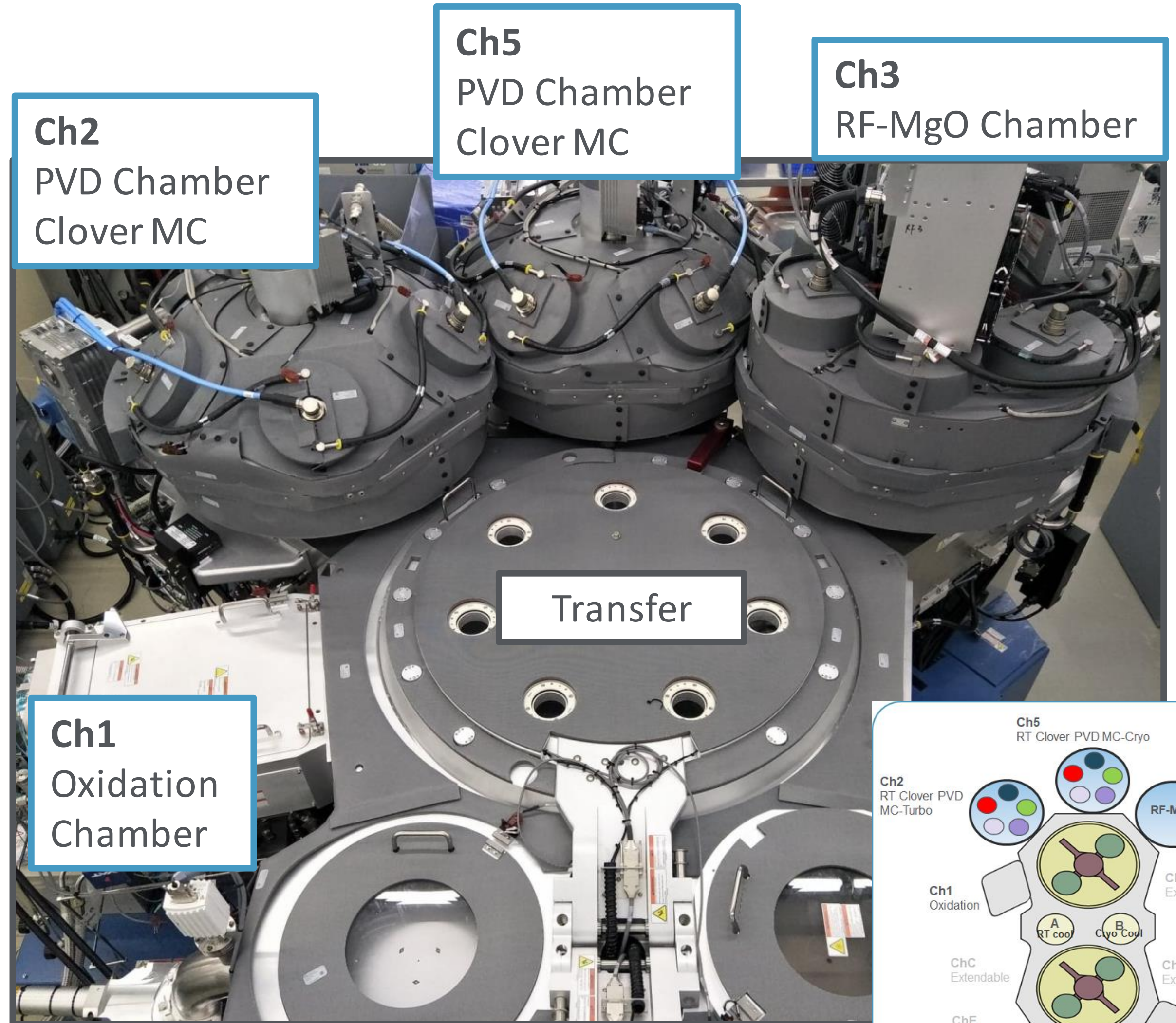
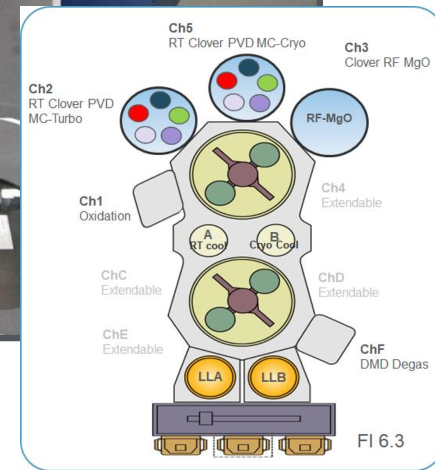
2.1 集結式主體結構







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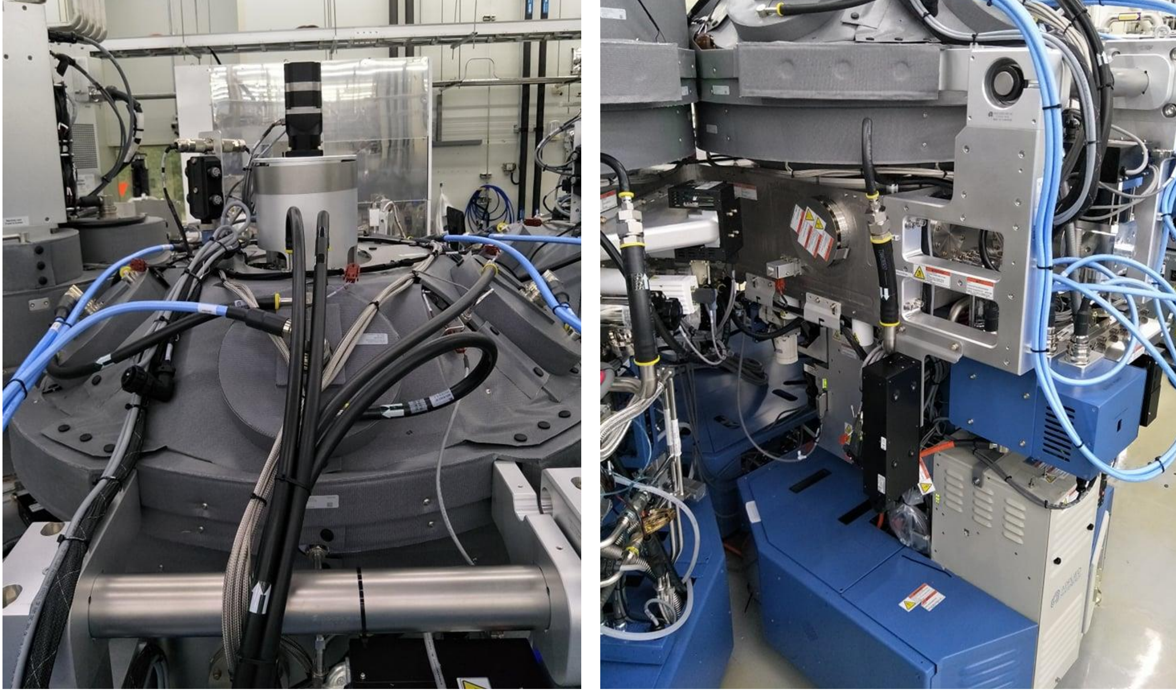
2.2 薄膜沉積腔體(PVD Chamber)

Clover PVD



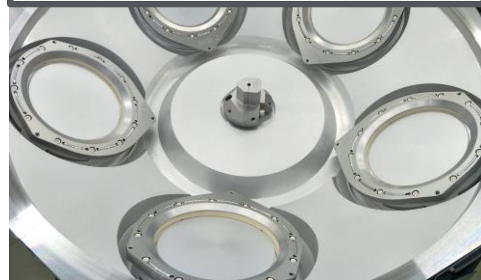
ESC

MKS DC Gen

MFC

Sumitomo Cryo Pump

Cathode X5



Adjust angle

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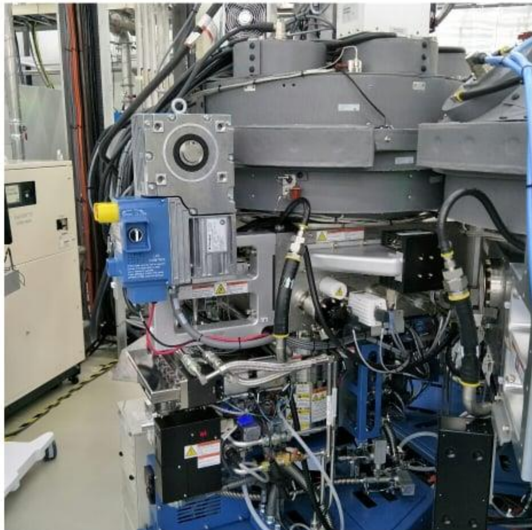
2.3 射頻氧化鎂薄膜沉積 (RF-MgO Chamber)

RF MgO



RF match

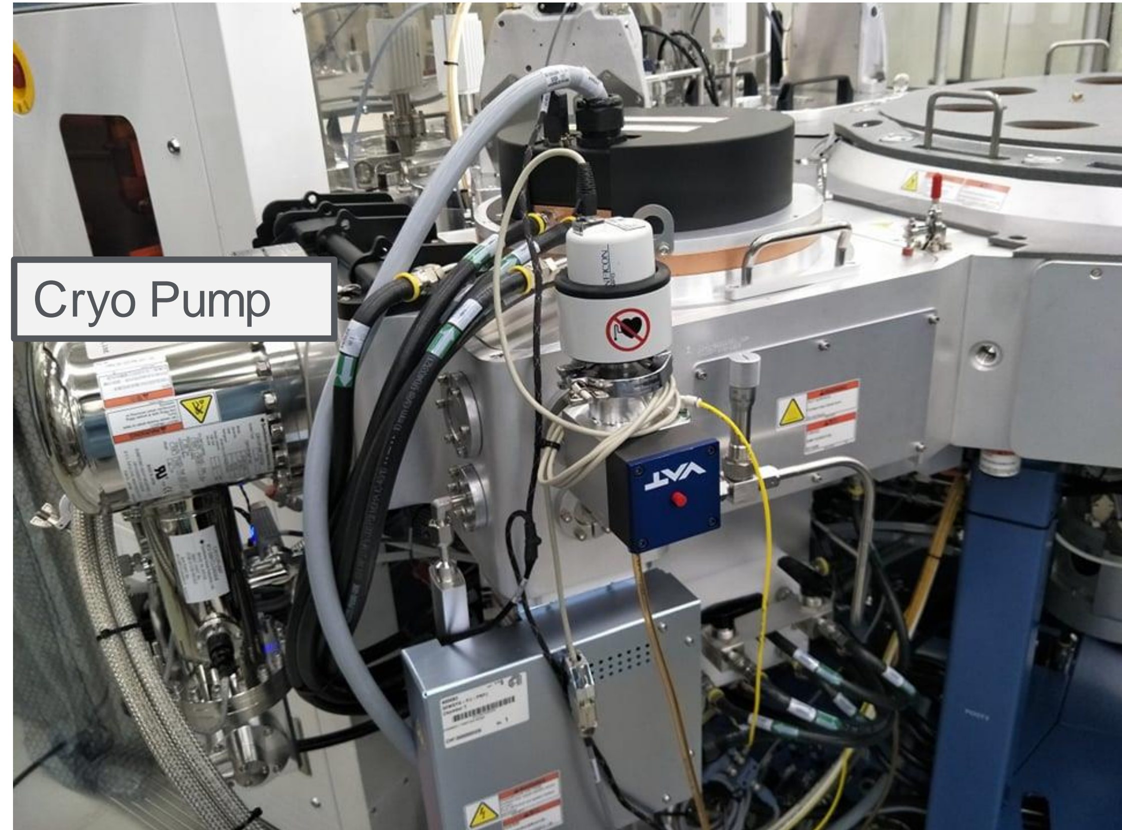
ESC

MFC

Sumitomo Cryo Pump

2.4 氧化製程腔體 (Oxidation)

2.5 釋氣腔體 (Dual Mode Degas)



2.6 真空系統

Chamber Position	Base pressure (Torr)	Base Pressure Spec (Torr)	Leak rate (nTorr/min)	Leak rate Spec (nTorr/min)
LLA	7.0E-8	≦1E-7	4998	≦8000
LLB	9.0E-8	≦1E-7	4999	≦8000
Buffer	3.3E-9	≦1E-8	0	≦1000
Transfer	4.1E-9	≦1E-8	2	≦1000
CH1	1.8E-8	≦1E-7	23.75	≦5000
CH2	1.9E-9	≦1E-8	8.87	≦200
CH3	1.2E-9	≦1E-8	15.54	≦200
CH5	1.8E-9	≦1E-8	10.80	≦200
CHF	7.6E-8	≦5E-7	567	≦1000

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2.7 超低溫冷卻系統

Cryo Pump

Cryo-Cool 1st temperature 100K
(Criteria < 110K)

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3. 控制模組

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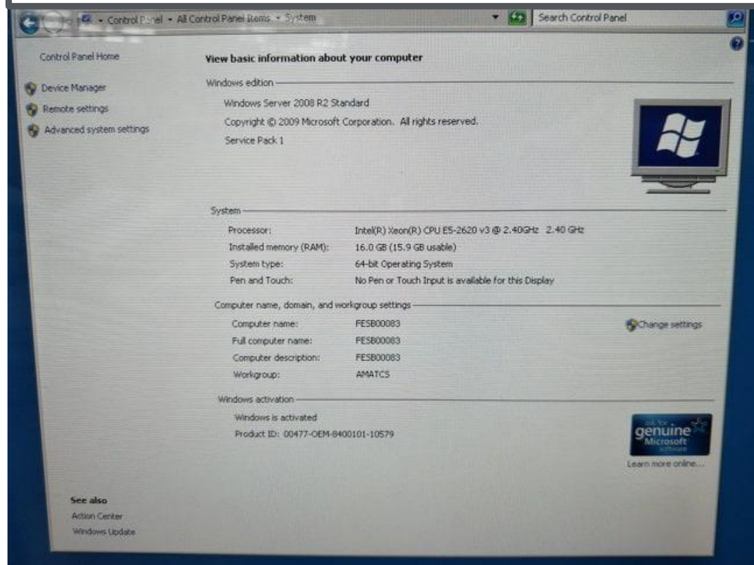
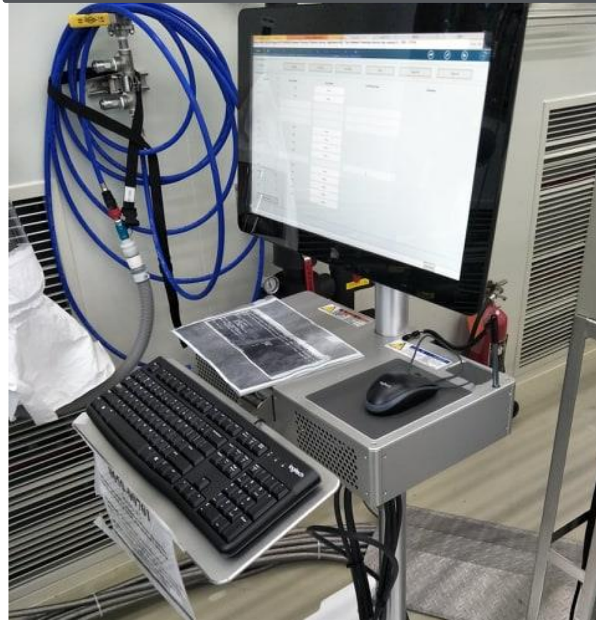
控制模組

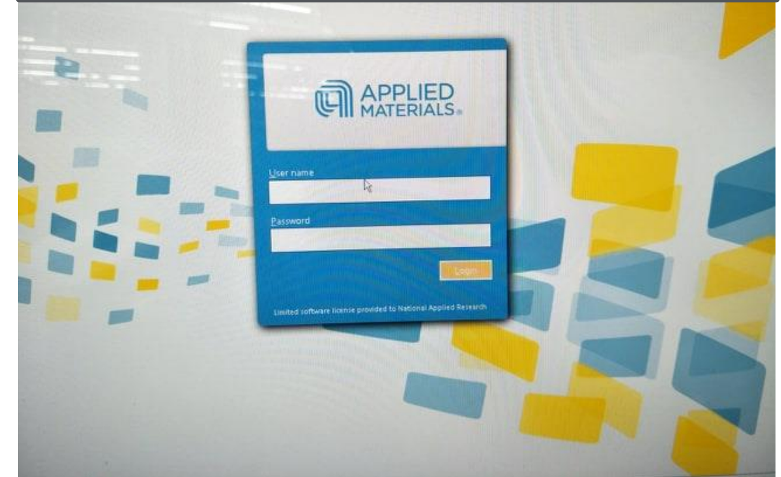
3.1 Windows Operation System



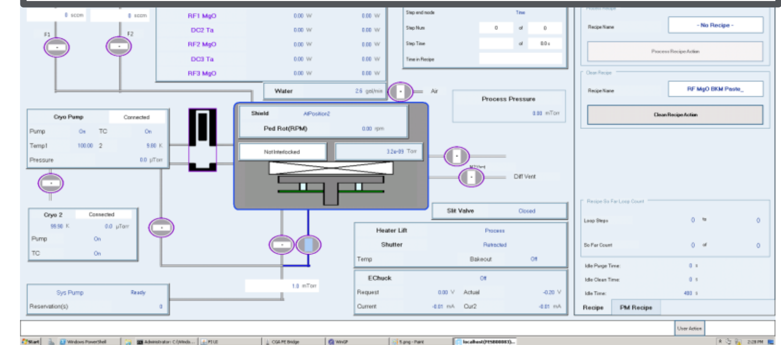
3.2 Monitor / Key board / Mouse X2



3.3 Authorization Access Interface



3.4 Control Interface



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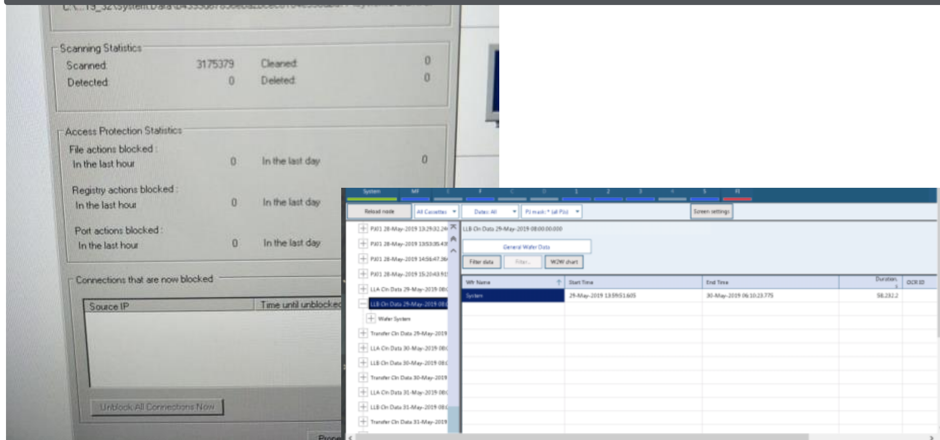
控制模組

5. Wafer History/ Anti-Virus Scan

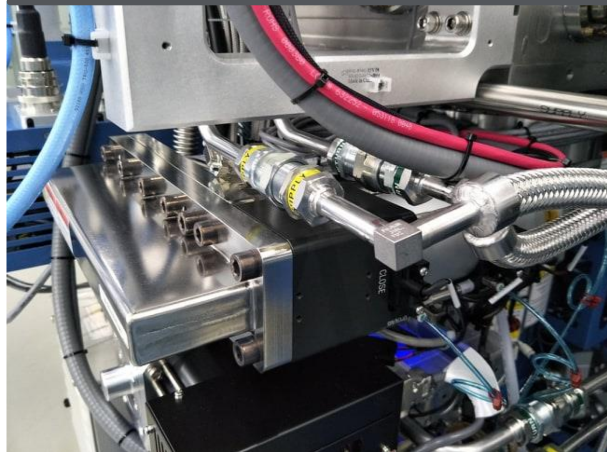


6. Parameter Offset Warning Function

7. Auto Recovery

8. DC Gen

8. Gate Valve



8. Heater Module

8. Cooling Water / Cooling System

控制模組

9.UPS

Light Tower

Helium Compressor